May 21, 2026

90th and 91st Issuance of Domestic Unsecured Straight Bonds

ACOM CO., LTD. has reached a decision to make its 90th and 91st issuance of domestic unsecured straight bonds, as outlined below. The funds procured through this issuance will be used for partial repayment of long-term borrowings.

Name of issuance	ACOM CO., LTD. 90th issuance of domestic unsecured straight bonds	ACOM CO., LTD. 91st issuance of domestic unsecured straight bonds
Total value	15 billion yen	14 billion yen
Interest rate	1.839% annually	2.541% annually
Individual bond value	100 million yen	100 million yen
Issue price	Face value 100 yen	Face value 100 yen
Redemption price	Face value 100 yen	Face value 100 yen
Application period	May 21, 2026	May 21, 2026
Payment date	May 27, 2026	May 27, 2026
Maturation date	May 26, 2028	May 27,2031
Application of funds procured	Partial repayment of long-term borrowings	Partial repayment of long-term borrowings
Trustee	Mitsubishi UFJ Morgan Stanley Securities Co., Ltd. SMBC Nikko Securities Inc. Daiwa Securities Co. Ltd. Nomura Securities Co., Ltd. Shinkin Securities Co.,Ltd.	Mitsubishi UFJ Morgan Stanley Securities Co., Ltd. SMBC Nikko Securities Inc. Daiwa Securities Co. Ltd. Nomura Securities Co., Ltd.
Transfer agent	MUFG Bank, Ltd.	
Credit ratings	Rating and Investment Information, Inc.: AA-	

ACOM CO., LTD.
Tokyo Shiodome Bldg., 1-9-1, Higashi-Shinbashi, Minato-ku, Tokyo, Japan